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**PRODUCT BULLETIN**  
**2005-05**

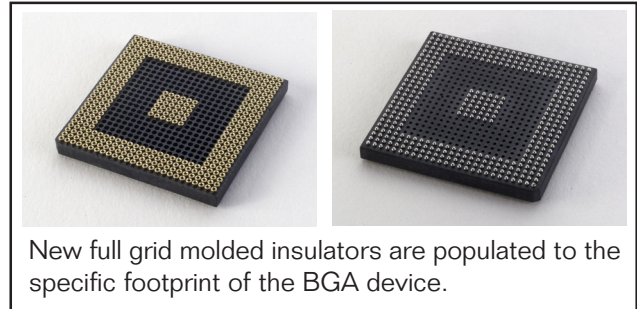
**PRODUCT IMPACT:**  
Molded BGA Sockets (1.27mm pitch)

**DATE:**  
November 16, 2005

**PART NUMBER SERIES:**  
RGS, RGSB

**TYPE:**  
Material Change

As part of our conversion to RoHS Compliant products, the molded insulator material for our 1.27mm pitch BGA Sockets has been changed from Polyphenylene Sulfide (PPS) to Liquid Crystal Polymer (LCP). The new LCP material is able to withstand the higher processing temperatures required in lead-free electronics manufacturing (up to 260° C for 40 seconds). See our RoHS Qualification Test Report, available online, for complete material qualification details. (Click on the Related Documents link in our Environmental Roadmap section at [www.advanced.com](http://www.advanced.com))



In addition to the material change, our new molded 1.27mm pitch BGA Sockets utilize a full-grid molded wafer (insulator), populated for any specific footprint to match the BGA device. This full-grid design improves air flow to dissipate heat from solder joints, reduces the overall mass of the socket, and will allow for shorter lead-times. To assist with accurate product selection and inventory issues, the part numbers have changed to reflect the new insulator material.

Body Type	Model Type	
	Standard Socket	Extraction Socket
Old PPS Material	MGS	MGSB
New LCP Material	RGS	RGSB

The new standard sockets (RGS) and extraction sockets (RGSB) are available in thru-hole and SMT designs for either lead-based or lead-free (RoHS Compliant) applications. The SMT models feature our industry-proven solder ball terminal design, available with either Tin/Lead (Sn/Pb) or RoHS Compliant, Tin/Silver/Copper (Sn/Ag/Cu) solder balls. The base terminal material (Brass), multi-finger contacts (Beryllium Copper) and Gold plating are all RoHS Compliant. See data sheet for complete details.

